



S/NA/0/623,788

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Leonard Forbes et al. Examiner: Pamela E. Perkins  
Serial No.: 10/623,788 Group Art Unit: 2822  
Filed: July 21, 2003 Docket: 1303.109US1  
Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

**COMMUNICATION CONCERNING RELATED APPLICATION(S)**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

| <u>Serial/Patent No.</u> | <u>Filing Date/Issue Date</u> | <u>Attorney Docket</u> | <u>Title</u>   |
|--------------------------|-------------------------------|------------------------|--|
| 11/210927                | August 24, 2005               | 1303.089US2            | MICRO-MECHANICALLY STRAINED SEMICONDUCTOR FILM         |
| 11/167894                | June 27, 2005                 | 1303.108US3            | GETTERING USING VOIDS FORMED BY SURFACE TRANSFORMATION |
| 11/210373                | August 24, 2005               | 1303.094US2            | STRAINED Si/SiGe STRUCTURES BY ION IMPLANTATION        |
| 11/214495                | August 29, 2005               | 1303.098US2            | SEMICONDUCTOR ON INSULATOR STRUCTURE                   |

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

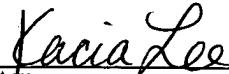
Respectfully submitted,  
LEONARD FORBES ET AL.

By Applicants' Representatives,  
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 373-6960

Date 10-31-05 By   
Marvin L. Beekman  
Reg. No. 38,377

**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 31 day of October, 2005.

Name KACIA LEE

Signature 

S/N 10/623,788



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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

LEONARD FORBES ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 373-6960

Date 10-31-05

By Marvin L. Beekman  
Marvin L. Beekman  
Reg. No. 38,377

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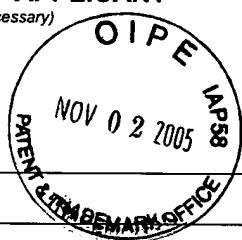
Name KACIA LEE

Signature Kacia Lee

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

|                             |                 |
|-----------------------------|-----------------|
| <b>Application Number</b>   | 10/623,788      |
| <b>Filing Date</b>          | July 21, 2003   |
| <b>First Named Inventor</b> | Forbes, Leonard |
| <b>Group Art Unit</b>       | 2822            |
| <b>Examiner Name</b>        | Perkins, Pamela |

Sheet 1 of 1

Attorney Docket No: 1303.109US1

**US PATENT DOCUMENTS**

| Examiner Initial * | USP Document Number | Publication Date | Name of Patentee or Applicant of cited Document | Filing Date If Appropriate |
|--------------------|---------------------|------------------|---|----------------------------|
|                    | US-2005/0087842-A1  | 04/28/2005       | Forbes, L.                                      | 11/02/2004                 |
|                    | US-5,858,819        | 01/12/1999       | Miyasaka, M.                                    | 02/15/1996                 |
|                    | US-6,107,661        | 08/22/2000       | Okabe, Naoto , et al.                           | 09/27/1996                 |
|                    | US-6,717,216        | 04/06/2004       | Doris, B. B., et al.                            | 12/12/2002                 |
|                    | US-6,825,102        | 11/30/2004       | Bedell, S. W., et al.                           | 09/18/2003                 |

**FOREIGN PATENT DOCUMENTS**

| Examiner Initials* | Foreign Document No | Publication Date | Name of Patentee or Applicant of cited Document | T <sup>2</sup> |
|--------------------|---------------------|------------------|---|----------------|
|                    |                     |                  |   |                |

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

| Examiner Initials* | Cite No <sup>1</sup> | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | T <sup>2</sup> |
|--------------------|----------------------|---|----------------|
|                    |                      | KAL, S. , et al., "Strained Silicon-SiGe Devices Using Germanium Implantation", IETE Journal of Research, 43 (2-3), (Mar. 1997),185-192   |                |
|                    |                      | XIAO, Q. , et al., "Preparation of thin Strained Si Film by Low Temperature Ge Ion Implantation and High Temperature Annealing", Solid-State and Integrated Circuits Technology, 2004. Proceedings 7th Int'l Conf., 3(3), (Oct. 18, 2004),2163-2166             |                |

**EXAMINER****DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup> Applicant's unique citation designation number (optional) <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached